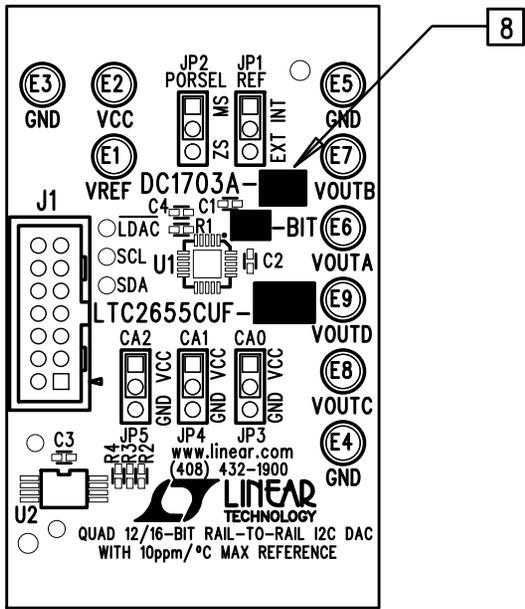
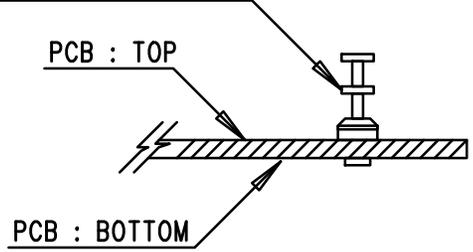


REVISION HISTORY				
ECO	REV	DESCRIPTION	APP. ENG.	DATE
-	2	PRODUCTION	LEO C.	04-11-11



NOTES: UNLESS OTHERWISE SPECIFIED

1. WORKMANSHIP SHALL BE IN ACCORDANCE WITH IPC-A-610.
2. ASSEMBLY PROCESS SHALL INCLUDE: REFLOW SOLDER TOP SIDE SMD. MAXIMUM SOLDER TEMPERATURE IS 240 DEG. C.
3. PARTS TO OMIT WILL BE SPECIFIED ON THE BILL OF MATERIALS. LOCATIONS OF OMITTED PARTS SHALL BE FREE OF SOLDER. MASK THE SOLDER STENCIL WHERE SMT PARTS ARE OMITTED.
4. INSTALL SHUNTS AS SHOWN ON ASSY DRAWING.
5. DEPANELIZE BOARDS AFTER ASSEMBLY AND ROUTE-OUT THE BREAKOUT TABS ON FOUR SIDES OF THE BOARD EDGE.
6. DO NOT APPLY ANY KIND OF ASSEMBLY STAMP OR QA STAMP TO ANY BOARD.
7. INSTALL TURRETS AS SHOWN BELOW:
(9 PLCS) : MILL-MAX 2308-2



8. MARK EACH LTC PART NUMBER, ASSEMBLY TYPE, AND NUMBER OF BIT WITH BLACK PERMANENT MARKER AS SHOWN IN TABLE BELOW:

ASSY	U1	-BIT
-A	LTC2655CUF-L16	16
-B	LTC2655CUF-H16	16
-C	LTC2655CUF-L12	12
-D	LTC2655CUF-H12	12

APPROVALS			
PCB DES.	KT	1630 MCCARTHY BLVD MILPITAS, CA 95035 PH: (408)432-1900 LTC CONFIDENTIAL- FOR CUSTOMER USE ONLY	
APP ENG.	LEO C.	TITLE: TOP ASSEMBLY DRAWING QUAD 12/16-BIT RAIL-TO-RAIL I2C DAC WITH 10ppm/°C MAX REFERENCE	
		SIZE N/A	IC NO. LTC2655CUF FAMILY DEMO CIRCUIT 1703A
			REV. 2
SCALE = NONE		FILENAME: DC1703A-2.PCB	SHT 1 OF 1